

## MEMS audio surface-mount bottom-port silicon microphone with analog output

Datasheet – preliminary data

### Features

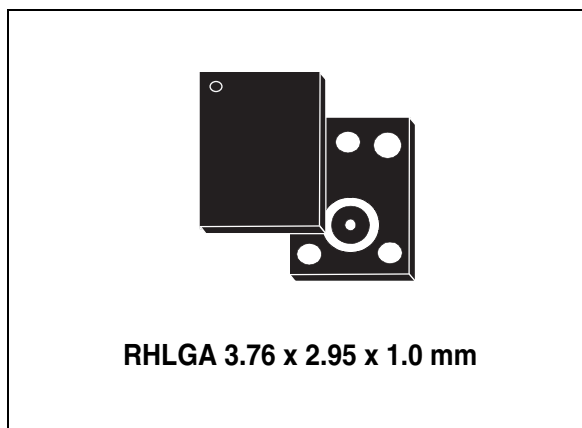
- Single supply voltage
- Low power consumption
- Omnidirectional sensitivity
- High signal-to-noise ratio
- High bandwidth
- Package compliant with reflow soldering

### Description

The MP33AB01H is a compact, low-power microphone built with a low-profile sensing element.

The sensing element, capable of detecting acoustic waves, is manufactured using a specialized silicon micromachining process to produce audio sensors.

The MP33AB01H has an acoustic overload point of 125 dB SPL with a 66 dB signal-to-noise ratio.



The MP33AB01H is available in a package compliant with reflow soldering and is guaranteed to operate over an extended temperature range from -30 °C to +100 °C.

**Table 1. Device summary**

Order code	Temperature range [°C]	Package	Packing
MP33AB01H	-30 to +100	RHLGA (3.76 x 2.95 x 1.0) mm	Tray
MP33AB01HTR	-30 to +100	RHLGA (3.76 x 2.95 x 1.0) mm	Tape and reel

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# 1 Pin description

Figure 1. Pin connections

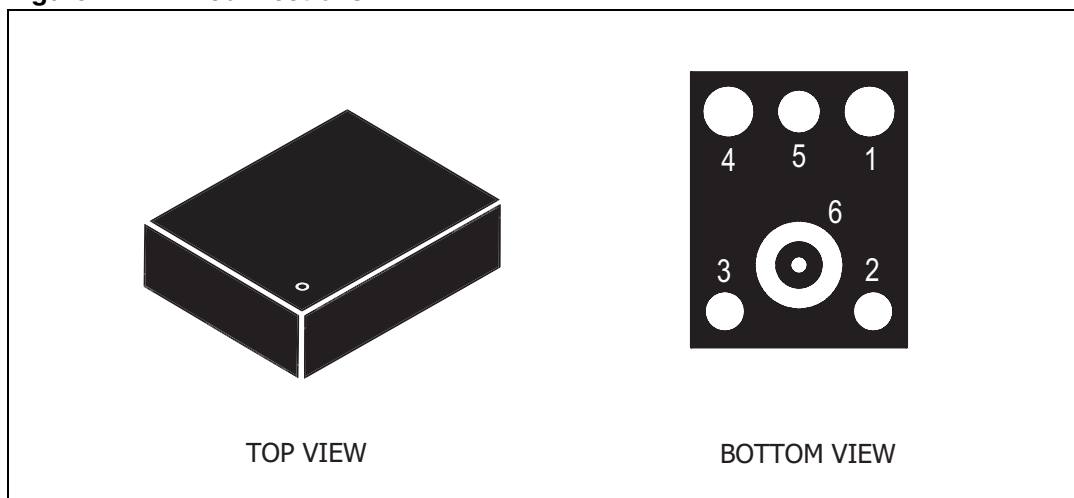


Table 2. Pin description

Pin #	Pin name	Function
1	Output	Analog output
2	GND	0 V supply
3	GND	0 V supply
4	Vdd	Power supply
5	GND	0 V supply
6	GND	0 V supply

## 2 Acoustic and electrical specifications

### 2.1 Acoustic and electrical characteristics

The values listed in the table below are specified for  $V_{dd} = 2.2\text{ V}$  unless otherwise noted.

**Table 3. Acoustic and electrical characteristics**

Symbol	Parameter	Test condition	Min.	Typ. <sup>(1)</sup>	Max.	Unit
Vdd	Supply voltage		1.5	2.2	3.6	V
Idd	Current consumption	mean value = 2 V			0.25	mA
FR	Frequency range		100		10000	Hz
So	Sensitivity	at 1 kHz (0 dB = 1 V/Pa)	-41	-38	-35	dBV
SNR	Signal-to-noise ratio	at 1 kHz (0 dB = 1 V/Pa)	64	66		dB
Top	Operating temperature range		-30		+100	°C

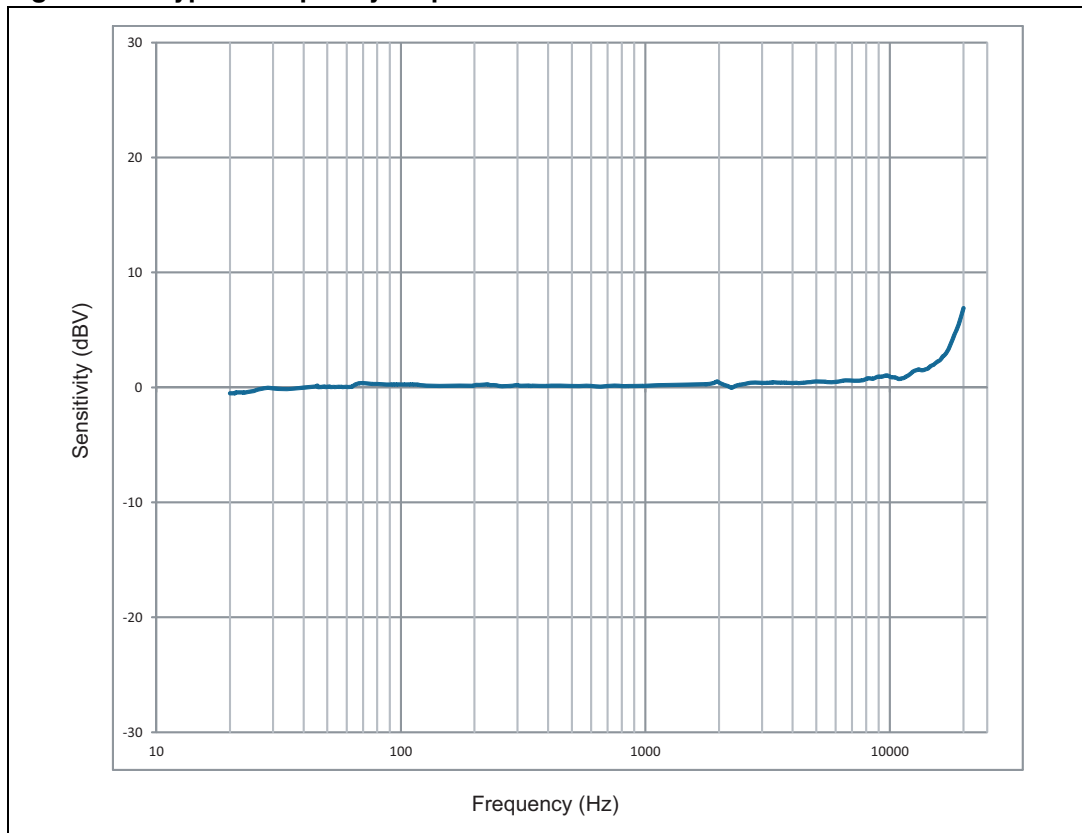
1. Typical specifications are not guaranteed.

**Table 4. Distortion specifications at 1 kHz**

Parameter	Test condition	Value
Distortion	94 dBSPL	< 1% THD
Distortion	125 dBSPL	10% THD (typ.)

## 2.2 Frequency response

Figure 2. Typical frequency response normalized at 1 kHz



### 3 Absolute maximum ratings

Stresses above those listed as “Absolute maximum ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device under these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

**Table 5. Absolute maximum ratings**

Symbol	Ratings	Maximum value	Unit
V <sub>dd</sub>	Supply voltage	-0.5 to 4	V
T <sub>STG</sub>	Storage temperature range	-40 to +100	°C



This device is sensitive to mechanical shock, improper handling can cause permanent damage to the part.

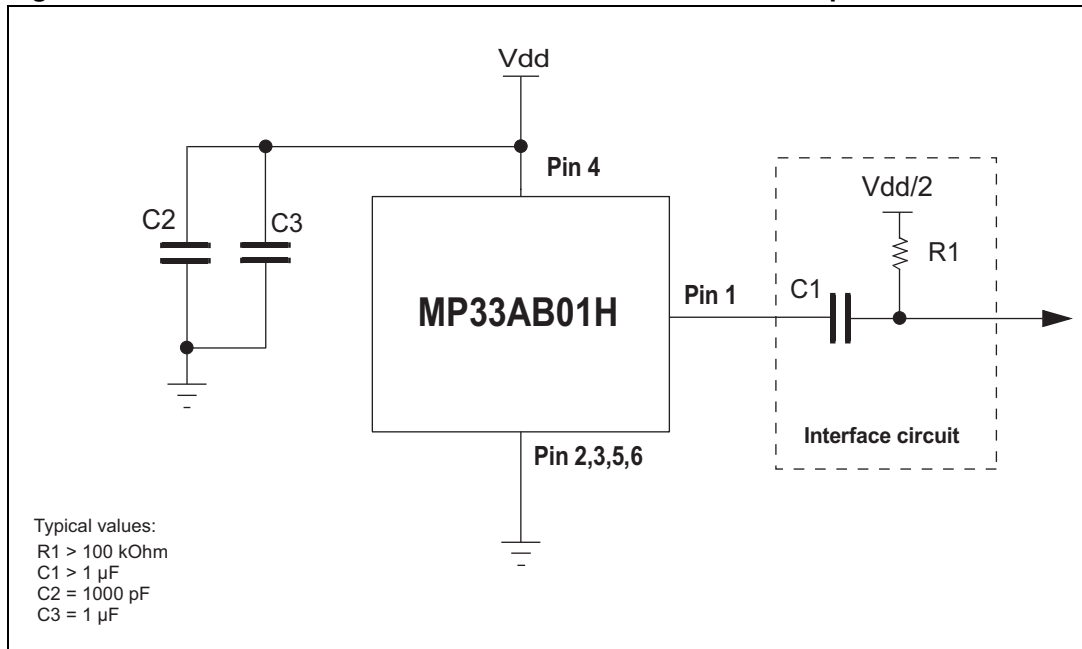


This device is ESD-sensitive, improper handling can cause permanent damage to the part.



## 4 Application recommendations

Figure 3. MP33AB01H electrical connections and external component values



## 5 Package mechanical data

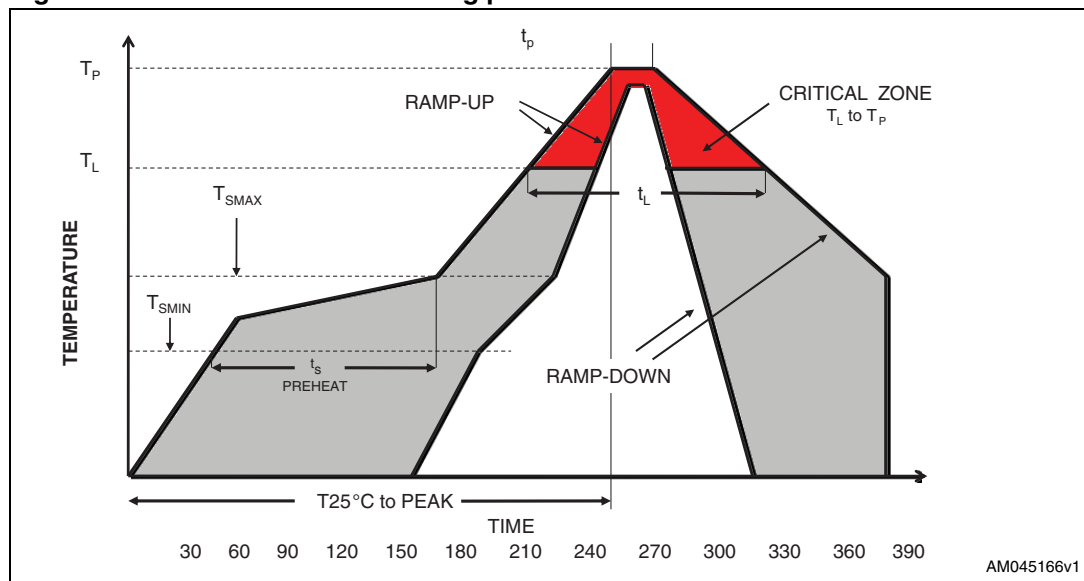
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### Soldering information

The RHLGA (3.76 x 2.95) mm package is also compliant with the RoHS and “Green” standards and is qualified for soldering heat resistance according to JEDEC J-STD-020.

Land pattern and soldering recommendations are available at [www.st.com](http://www.st.com).

**Figure 4. Recommended soldering profile limits**



**Table 6. Recommended soldering profile limits**

Description	Parameter	Pb free
Average ramp rate	$T_L$ to $T_P$	3 °C/sec max
Preheat		
Minimum temperature	$T_{SMIN}$	150 °C
Maximum temperature	$T_{SMAX}$	200 °C
Time ( $T_{SMIN}$ to $T_{SMAX}$ )	$t_s$	60 sec to 120 sec
Ramp-up rate	$T_{SMAX}$ to $T_L$	
Time maintained above liquidous temperature	$t_L$	60 sec to 150 sec
Liquidous temperature	$T_L$	217 °C
Peak temperature	$T_P$	260 °C max
Time within 5 °C of actual peak temperature		20 sec to 40 sec
Ramp-down rate		6 °C/sec max
Time 25 °C ( $t_{25\text{ °C}}$ ) to peak temperature		8 minutes max

Figure 5. RHLGA 3.76 mm x 2.95 mm x 1.0 mm package outline

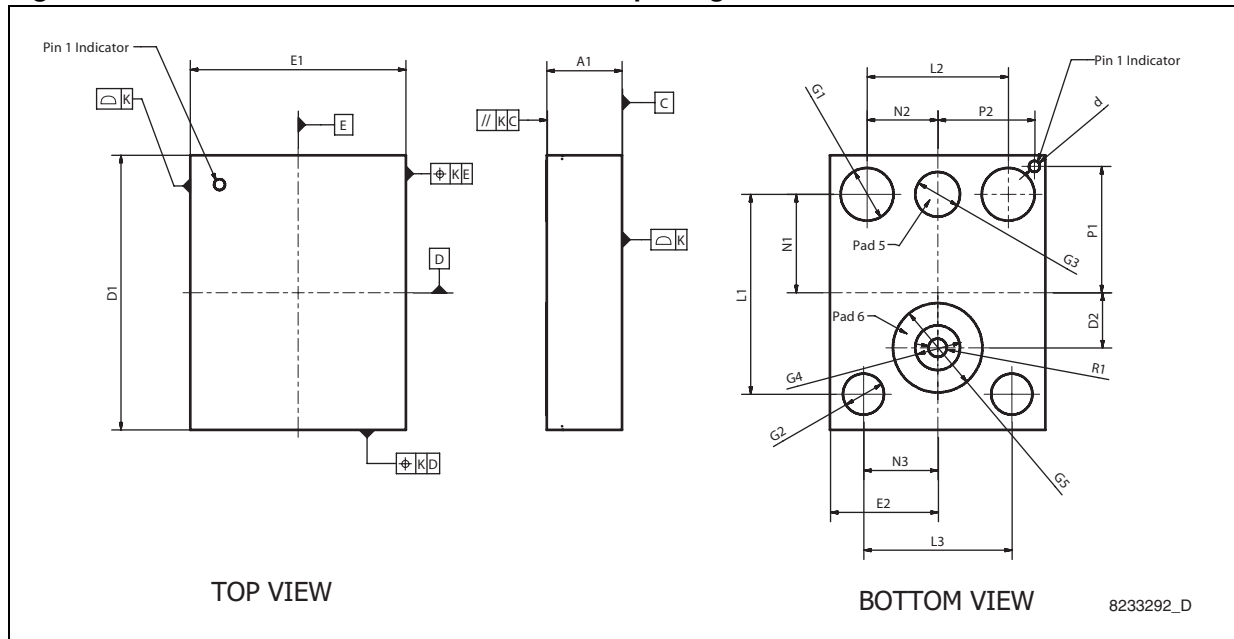


Table 7. RHLGA 3.76 mm x 2.95 mm x 1.0 mm package dimensions

Symbol	mm			in		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A1	0.900	1.000	1.100	0.0354	0.0394	0.0433
D1	3.660	3.760	3.860	0.1441	0.1480	0.1520
D2	0.600	0.750	0.900	0.0236	0.0295	0.0354
R1	0.200	0.250	0.300	0.0079	0.0098	0.0118
E1	2.850	2.950	3.050	0.1122	0.1161	0.1201
E2	1.325	1.475	1.625	0.0522	0.0581	0.0640
L1	2.690	2.740	2.790	0.1059	0.1079	0.1098
L2	1.882	1.932	1.982	0.0741	0.0761	0.0780
L3	1.981	2.031	2.181	0.0780	0.0800	0.0859
N1	1.300	1.350	1.400	0.0512	0.0531	0.0551
N2	0.916	0.966	1.116	0.0361	0.0380	0.0440
N3	0.965	1.015	1.065	0.0380	0.0400	0.0419
G1	0.673	0.723	0.763	0.0265	0.0285	0.0300
G2	0.512	0.562	0.612	0.0202	0.0221	0.0241
G3	0.562	0.612	0.662	0.0221	0.0241	0.0261
G4	0.562	0.612	0.662	0.0221	0.0241	0.0261
G5	1.174	1.224	1.274	0.0462	0.0482	0.0502
P1	1.680	1.730	1.780	0.0661	0.0681	0.0701
P2	1.275	1.325	1.375	0.0502	0.0522	0.0541
d		0.150			0.0059	
K		0.050			0.0020	

Figure 6. Device footprint and PCB land pattern

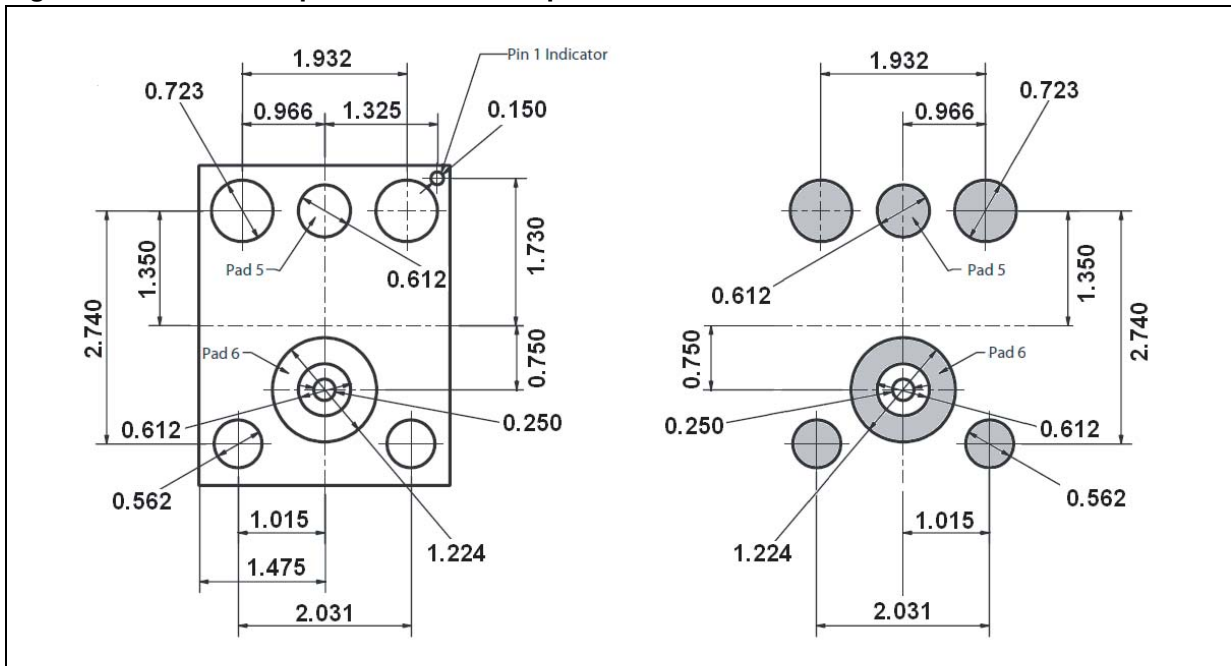
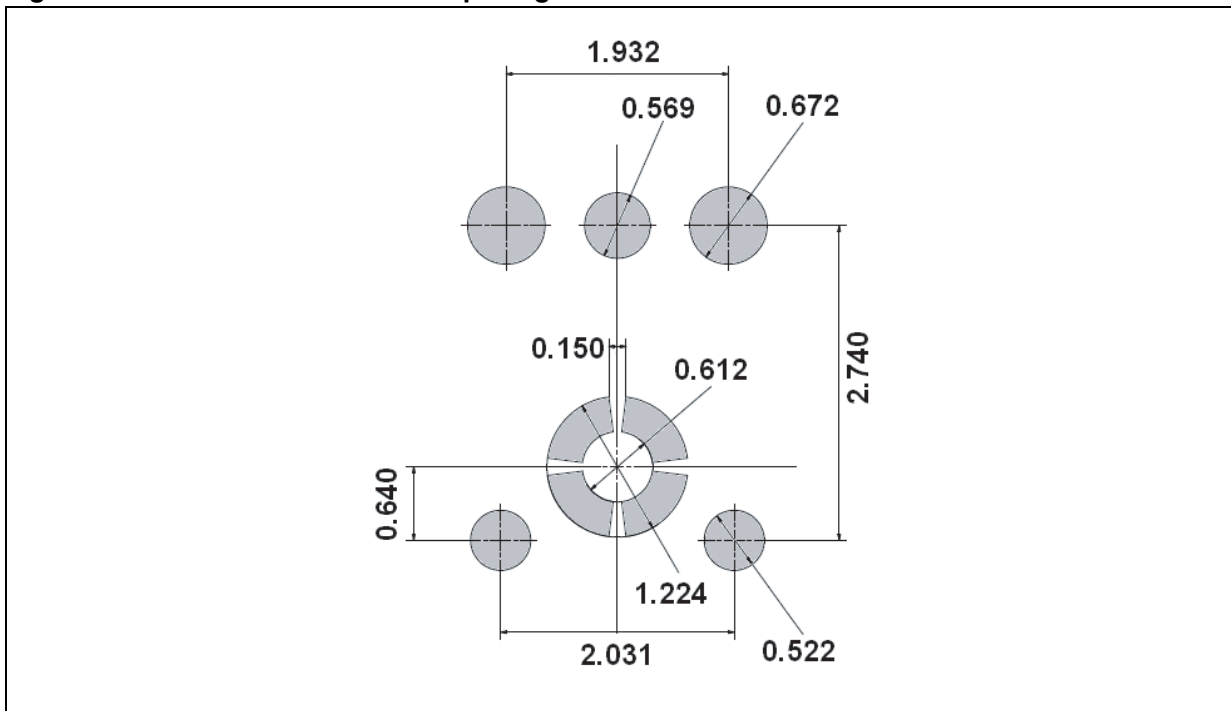


Figure 7. Recommended stencil openings



## 6 Revision history

**Table 8. Document revision history**

Date	Revision	Changes
17-Jan-2013	1	Initial release

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